Renesas Electronics America Inc - R5F562T7EDFM#V1 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	I²C, LINbus, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	37
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f562t7edfm-v1

Table 1.2 Functions of RX62T Group and RX62G Group Products (2 / 2)

Functions	RX62G Group		RX62T Group				
Pin number	**112 Pins**	**100 Pins**	**112 Pins**	**100 Pins**	**80 Pins (R5F562T xGDFF)**	**80 Pins**	**64 Pins**
Package	LQFP2020 (0.65-mm pitch)	LQFP1414 (0.5-mm pitch)	LQFP2020 (0.65-mm pitch)	LQFP1414 (0.5-mm pitch)	LQFP1414 (0.65-mm pitch)	LQFP1414 (0.65-mm pitch)	LQFP1010 (0.5-mm pitch) LQFP1414 (0.8-mm pitch)

O: Supported, —: Not supported

Note 1. For the MTU and GPT, the number of pins will differ with the package. See the list of pins and pin functions for details. In addition, the CAN module is an optional function. See Table 1.3 for details.

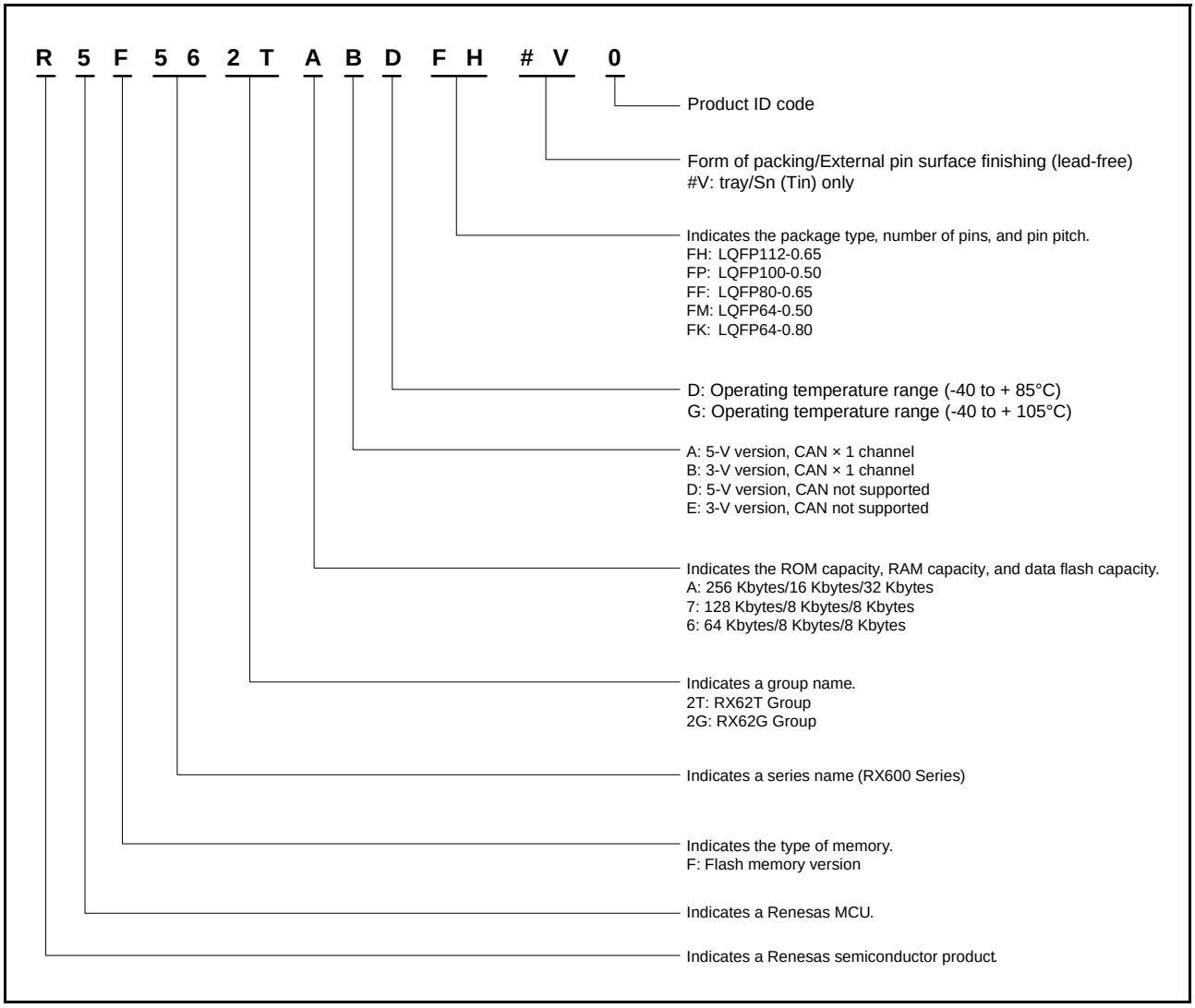


Figure 1.1 How to Read the Product Part No.

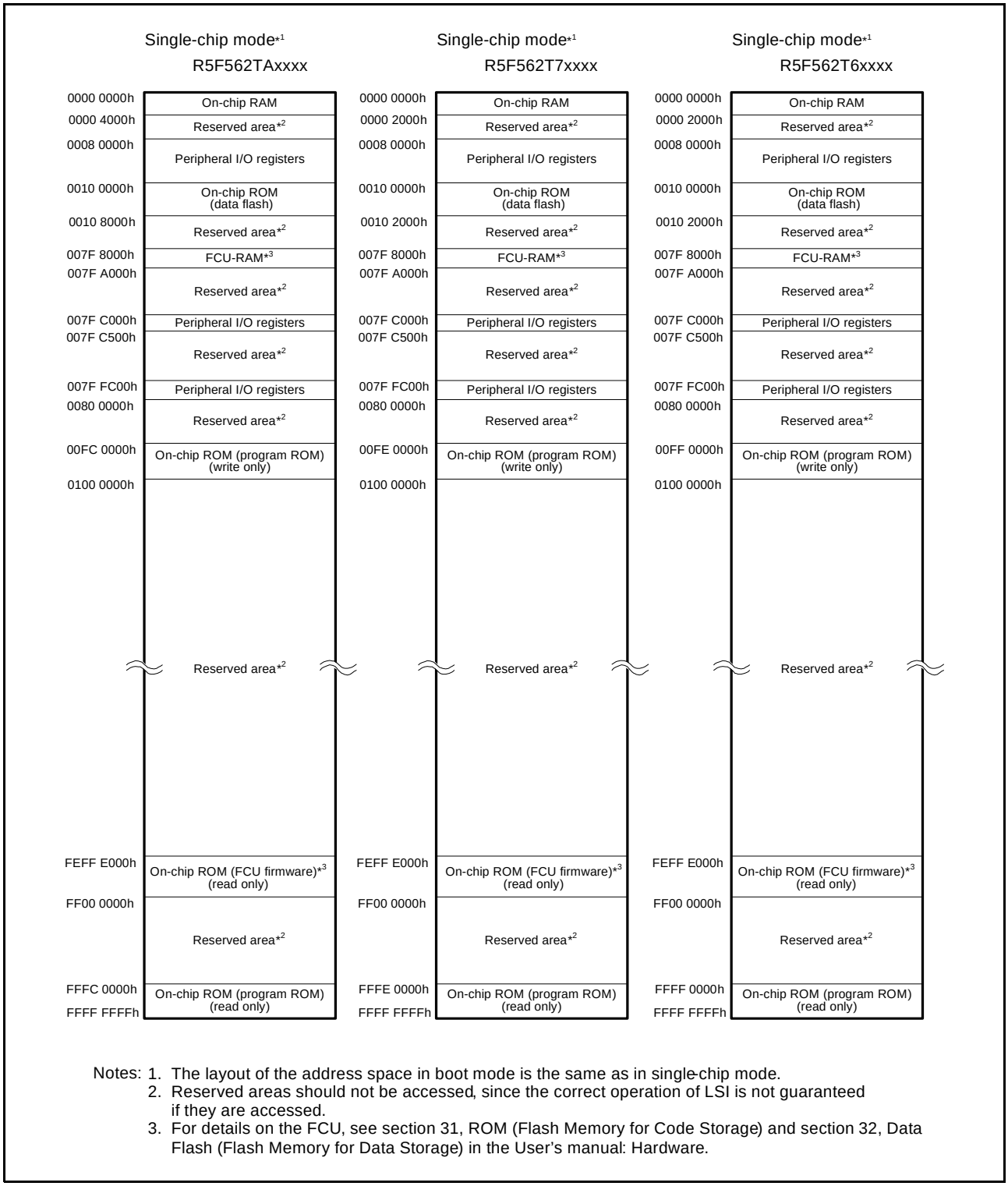
Table 1.6 List of Pins and Pin Functions (80-Pin LQFP) (1 / 3)

Pin No. (80-Pin LQFP)	Power Supply Clock System Control	I/O Port	Analog	Timer	Communi-cation	Interrupt	POE	Debugging
1	EMLE							
2	VSS							
3	MDE							
4	VCL							
5	MD1							
6	MD0							
7		PE4		MTCLKC-C		IRQ1-B	POE10#-B	
8		PE3		MTCLKD-C		IRQ2-A	POE11#	
9	RES#							
10	XTAL							
11	VSS							
12	EXTAL							
13	VCC							
14		PE2				NMI	POE10#-A	
15		PE0			CRX-C			
16		PD7		GTIOC0A-B	CTX-C			TRST#
17		PD6		GTIOC0B-B				TMS
18		PD5		GTIOC1A-B	RXD1			TDI
19		PD4		GTIOC1B-B	SCK1			TCK
20		PD3		GTIOC2A-B	TXD1			TDO
21		PB7			SCK2-A			
22		PB6			CRX-A/ RXD2-A			
23		PB5			CTX-A/ TXD2-A			
24	PLLVCC							
25		PB4		GTETRG		IRQ3	POE8#	
26	PLLVSS							
27		PB3		MTIOC0A-A	SCK0			
28		PB2		MTIOC0B-A	TXD0/SDA			
29		PB1		MTIOC0C	RXD0/SCL			
30		PB0		MTIOC0D	MOSI-B			
31		PA3		MTIOC2A	SSL0-B			
32		PA2		MTIOC2B	SSL1-B			
33	VCC							
34		P96				IRQ4	POE4#	
35	VSS							
36		P95		MTIOC6B				
37		P94		MTIOC7A				
38		P93		MTIOC7B				
39		P92		MTIOC6D				
40		P91		MTIOC7C				
41		P76		MTIOC4D/ GTIOC2B-A				

3. Address Space

3.1 Address Space

This LSI has a 4-Gbyte address space, consisting of the range of addresses from 0000 0000h to FFFF FFFFh. That is, linear access to an address space of up to 4 Gbytes is possible, and this contains both program and data areas. Figure 3.1 shows the memory maps.



Notes: 1. The layout of the address space in boot mode is the same as in single-chip mode.
2. Reserved areas should not be accessed, since the correct operation of LSI is not guaranteed if they are accessed.
3. For details on the FCU, see section 31, ROM (Flash Memory for Code Storage) and section 32, Data Flash (Flash Memory for Data Storage) in the User's manual: Hardware.

Figure 3.1 Memory Map (RX62T Group)

(a) Write to an I/O register.

(b) Read the value from the I/O register to a general register.

(c) Execute the operation using the value read.

(d) Execute the subsequent instruction.

[Instruction examples]

- Byte-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.B  #SFR_DATA, [R1]
CMP    [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.W  #SFR_DATA, [R1]
CMP    [R1].W, R1
;; Next process
```

- Longword-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.L  #SFR_DATA, [R1]
CMP    [R1].L, R1
;; Next process
```

If multiple registers are written to and a subsequent instruction should be executed after the write operations are entirely completed, only read the I/O register that was last written to and execute the operation using the value; it is not necessary to read or execute operation for all the registers that were written to.

Table 4.1 List of I/O Registers (Address Order) (17 / 25)

Address	Module Abbreviation	Register Name	Register Abbreviation	Number of Bits	Access Size	Number of Access Cycles
000C 123Ah	MTU	Timer interrupt skipping mode register A	TITMRA	8	8	5 ICLK
000C 123Bh	MTU	Timer interrupt skipping set register 2A	TITCR2A	8	8	5 ICLK
000C 123Ch	MTU	Timer interrupt skipping counter 2A	TITCNT2A	8	8	5 ICLK
000C 1240h	MTU4	Timer A/D converter start request control register	TADCR	16	16	5 ICLK
000C 1244h	MTU4	Timer A/D converter start request cycle set register A	TADCORA	16	16, 32	5 ICLK
000C 1246h	MTU4	Timer A/D converter start request cycle set register B	TADCORB	16	16	5 ICLK
000C 1248h	MTU4	Timer A/D converter start request cycle set buffer register A	TADCOBRA	16	16, 32	5 ICLK
000C 124Ah	MTU4	Timer A/D converter start request cycle set buffer register B	TADCOBRB	16	16	5 ICLK
000C 1260h	MTU	Timer waveform control register A	TWCRA	8	8	5 ICLK
000C 1270h	MTU3	Timer mode register 2A	TMDR2A	8	8	5 ICLK
000C 1272h	MTU3	Timer general register E	TGRE	16	16	5 ICLK
000C 1274h	MTU4	Timer general register E	TGRE	16	16	5 ICLK
000C 1276h	MTU4	Timer general register F	TGRF	16	16	5 ICLK
000C 1280h	MTU	Timer start register A	TSTRA	8	8, 16	5 ICLK
000C 1281h	MTU	Timer synchronous register A	TSYRA	8	8	5 ICLK
000C 1282h	MTU	Timer counter synchronous start register	TCSYSTR	8	8	5 ICLK
000C 1284h	MTU	Timer read/write enable register A	TRWERA	8	8	5 ICLK
000C 1300h	MTU0	Timer control register	TCR	8	8, 16, 32	5 ICLK
000C 1301h	MTU0	Timer mode register 1	TMDR1	8	8	5 ICLK
000C 1302h	MTU0	Timer I/O control register H	TIORH	8	8, 16	5 ICLK
000C 1303h	MTU0	Timer I/O control register L	TIORL	8	8	5 ICLK
000C 1304h	MTU0	Timer interrupt enable register	TIER	8	8, 16, 32	5 ICLK
000C 1305h	MTU0	Timer status register	TSR	8	8	5 ICLK
000C 1306h	MTU0	Timer counter	TCNT	16	16	5 ICLK
000C 1308h	MTU0	Timer general register A	TGRA	16	16, 32	5 ICLK
000C 130Ah	MTU0	Timer general register B	TGRB	16	16	5 ICLK
000C 130Ch	MTU0	Timer general register C	TGRC	16	16, 32	5 ICLK
000C 130Eh	MTU0	Timer general register D	TGRD	16	16	5 ICLK
000C 1320h	MTU0	Timer general register E	TGRE	16	16, 32	5 ICLK
000C 1322h	MTU0	Timer general register F	TGRF	16	16	5 ICLK
000C 1324h	MTU0	Timer interrupt enable register 2	TIER2	8	8, 16	5 ICLK
000C 1325h	MTU0	Timer status register 2	TSR2	8	8	5 ICLK
000C 1326h	MTU0	Timer buffer operation transfer mode register	TBTM	8	8	5 ICLK
000C 1380h	MTU1	Timer control register	TCR	8	8, 16	5 ICLK
000C 1381h	MTU1	Timer mode register 1	TMDR1	8	8	5 ICLK
000C 1382h	MTU1	Timer I/O control register	TIOR	8	8	5 ICLK
000C 1384h	MTU1	Timer interrupt enable register	TIER	8	8, 16, 32	5 ICLK
000C 1385h	MTU1	Timer status register	TSR	8	8	5 ICLK
000C 1386h	MTU1	Timer counter	TCNT	16	16	5 ICLK
000C 1388h	MTU1	Timer general register A	TGRA	16	16, 32	5 ICLK
000C 138Ah	MTU1	Timer general register B	TGRB	16	16	5 ICLK

Table 4.2 List of I/O Registers (Bit Order) (7 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
ICU	DTCER180	—	—	—	—	—	—	—	DTCE
ICU	DTCER181	—	—	—	—	—	—	—	DTCE
ICU	DTCER182	—	—	—	—	—	—	—	DTCE
ICU	DTCER183	—	—	—	—	—	—	—	DTCE
ICU	DTCER184	—	—	—	—	—	—	—	DTCE
ICU	DTCER186	—	—	—	—	—	—	—	DTCE
ICU	DTCER187	—	—	—	—	—	—	—	DTCE
ICU	DTCER188	—	—	—	—	—	—	—	DTCE
ICU	DTCER189	—	—	—	—	—	—	—	DTCE
ICU	DTCER190	—	—	—	—	—	—	—	DTCE
ICU	DTCER192	—	—	—	—	—	—	—	DTCE
ICU	DTCER193	—	—	—	—	—	—	—	DTCE
ICU	DTCER194	—	—	—	—	—	—	—	DTCE
ICU	DTCER195	—	—	—	—	—	—	—	DTCE
ICU	DTCER196	—	—	—	—	—	—	—	DTCE
ICU	DTCER215	—	—	—	—	—	—	—	DTCE
ICU	DTCER216	—	—	—	—	—	—	—	DTCE
ICU	DTCER219	—	—	—	—	—	—	—	DTCE
ICU	DTCER220	—	—	—	—	—	—	—	DTCE
ICU	DTCER223	—	—	—	—	—	—	—	DTCE
ICU	DTCER224	—	—	—	—	—	—	—	DTCE
ICU	DTCER247	—	—	—	—	—	—	—	DTCE
ICU	DTCER248	—	—	—	—	—	—	—	DTCE
ICU	DTCER254	—	—	—	—	—	—	—	DTCE
ICU	IER02	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER03	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER05	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER07	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER08	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER0C	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER0D	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER0E	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER0F	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER10	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER11	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER12	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER13	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER15	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER16	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER17	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER18	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER1A	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER1B	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER1C	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER1E	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	IER1F	IEN7	IEN6	IEN5	IEN4	IEN3	IEN2	IEN1	IEN0
ICU	SWINTR	—	—	—	—	—	—	—	SWINT
ICU	FIR	FIEN	—	—	—	—	—	—	—
		FVCT[7:0]							
ICU	IPR00	—	—	—	—	IPR[3:0]			
ICU	IPR01	—	—	—	—	IPR[3:0]			
ICU	IPR02	—	—	—	—	IPR[3:0]			

Table 4.2 List of I/O Registers (Bit Order) (12 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
RSPI0	SSLP	—	—	—	—	SSLP3	SSLP2	SSLP1	SSLP0
RSPI0	SPPCR	—	—	MOIFE	MOIFV	—	—	SPLP2	SPLP
RSPI0	SPSR	SPRF	—	SPTEF	—	PERF	MODF	IDLNF	OVRF
RSPI0	SPDR	H[15:0]							
		H[15:0]							
		L[15:0]							
		L[15:0]							
RSPI0	SPSCR	—	—	—	—	—		SPSLN[2:0]	
RSPI0	SPSSR	—		SPECM[2:0]		—		SPCP[2:0]	
RSPI0	SPBR	SPR7	SPR6	SPR5	SPR4	SPR3	SPR2	SPR1	SPR0
RSPI0	SPDCR	—	—	SPLW	SPRDTD	SLSEL[1:0]		SPFC[1:0]	
RSPI0	SPCKD	—	—	—	—	—		SCKDL[2:0]	
RSPI0	SSLND	—	—	—	—	—		SLNDL[2:0]	
RSPI0	SPND	—	—	—	—	—		SPNDL[2:0]	
RSPI0	SPCR2	—	—	—	—	PTE	SPIIE	SPOE	SPPE
RSPI0	SPCMD0	SCKDEN	SLNDEN	SPNDEN	LSBF		SPB[3:0]		
		SSLKP		SSLA[2:0]		BRDV[1:0]		CPOL	CPHA
RSPI0	SPCMD1	SCKDEN	SLNDEN	SPNDEN	LSBF		SPB[3:0]		
		SSLKP		SSLA[2:0]		BRDV[1:0]		CPOL	CPHA
RSPI0	SPCMD2	SCKDEN	SLNDEN	SPNDEN	LSBF		SPB[3:0]		
		SSLKP		SSLA[2:0]		BRDV[1:0]		CPOL	CPHA
RSPI0	SPCMD3	SCKDEN	SLNDEN	SPNDEN	LSBF		SPB[3:0]		
		SSLKP		SSLA[2:0]		BRDV[1:0]		CPOL	CPHA
RSPI0	SPCMD4	SCKDEN	SLNDEN	SPNDEN	LSBF		SPB[3:0]		
		SSLKP		SSLA[2:0]		BRDV[1:0]		CPOL	CPHA
RSPI0	SPCMD5	SCKDEN	SLNDEN	SPNDEN	LSBF		SPB[3:0]		
		SSLKP		SSLA[2:0]		BRDV[1:0]		CPOL	CPHA
RSPI0	SPCMD6	SCKDEN	SLNDEN	SPNDEN	LSBF		SPB[3:0]		
		SSLKP		SSLA[2:0]		BRDV[1:0]		CPOL	CPHA
RSPI0	SPCMD7	SCKDEN	SLNDEN	SPNDEN	LSBF		SPB[3:0]		
		SSLKP		SSLA[2:0]		BRDV[1:0]		CPOL	CPHA
S12AD0	ADCSR	ADST	ADCS[1:0]		ADIE	CKS[1:0]		TRGE	EXTRG
S12AD0	ADANS	—	—	CH[1:0]		—	PG002SEL	PG001SEL	PG000SEL
		—	—	—	—	—	PG002EN	PG001EN	PG000EN
S12AD0	ADPG	—	—	—	—	PG002GAIN[3:0]			
		PG001GAIN[3:0]				PG000GAIN[3:0]			
S12AD0	ADCER	ADRFMT	—	ADIEW	ADIE2	DIAGM	DIAGLD	DIAGVAL[1:0]	
		—	—	ACE	—	—	ADPRC[1:0]		SHBYP
S12AD0	ADSTRGR	—	—	—	ADSTRS1[4:0]				
		—	—	—	ADSTRS0[4:0]				
S12AD	ADCMPMD0	—	—	CEN102[1:0]		CEN101[1:0]		CEN100[1:0]	
		—	—	CEN002[1:0]		CEN001[1:0]		CEN000[1:0]	
S12AD	ADCMPMD1	—	VSELL1	VSELH1	CSEL1	—	VSELL0	VSELH0	CSEL0
		—		REFH[2:0]		—		REFL[2:0]	
S12AD	ADCMPNR0	—	—	—	—	C002NR[3:0]			
		C001NR[3:0]				C000NR[3:0]			
S12AD	ADCMPNR1	—	—	—	—	C102NR[3:0]			
		C101NR[3:0]				C100NR[3:0]			
S12AD	ADCMPFR	—	—	C102FLAG	C101FLAG	C100FLAG	C002FLAG	C001FLAG	C000FLAG
S12AD	ADCMPSEL	—	—	—	—	—	—	POERQ	IE
		—	—	SEL102	SEL101	SEL100	SEL002	SEL001	SEL000

Table 4.2 List of I/O Registers (Bit Order) (21 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
MTU7	TIORL	IOD[3:0]				IOC[3:0]			
MTU6	TIER	TTEG	—	—	TCIEV	TGIED	TGIEC	TGIEB	TGIEA
MTU7	TIER	TTEG	TTEG2	—	TCIEV	TGIED	TGIEC	TGIEB	TGIEA
MTU	TOERB	—	—	OE7D	OE7C	OE6D	OE7B	OE7A	OE6B
MTU	TOCR1B	—	PSYE	—	—	TOCL	TOCS	OLSN	OLSP
MTU6	TCNT								
MTU7	TCNT								
MTU	TCDRB								
MTU	TDDRB								
MTU6	TGRA								
MTU6	TGRB								
MTU7	TGRA								
MTU7	TGRB								
MTU	TCNTSB								
MTU	TCBRB								
MTU6	TGRC								
MTU6	TGRD								
MTU7	TGRC								
MTU7	TGRD								
MTU6	TSR	TCFD	—	—	TCFV	TGFD	TGFC	TGFB	TGFA
MTU7	TSR	TCFD	—	—	TCFV	TGFD	TGFC	TGFB	TGFA
MTU	TITCR1B	T6AEN		T6ACOR[2:0]		T7VEN		T7VCOR[2:0]	
MTU	TITCNT1B	—		T6ACNT[2:0]		—		T7VCNT[2:0]	
MTU	TBTERB	—	—	—	—	—	—	BTE[1:0]	
MTU	TDERB	—	—	—	—	—	—	—	TDER
MTU	TOLBRB	—	—	OLS3N	OLS3P	OLS2N	OLS2P	OLS1N	OLS1P
MTU6	TBTM	—	—	—	—	—	—	TTSB	TTSA
MTU7	TBTM	—	—	—	—	—	—	TTSB	TTSA
MTU	TITMRB	—	—	—	—	—	—	—	TITM
MTU	TITCR2B	—	—	—	—	—		TRGCOR[2:0]	
MTU	TITCNT2B	—	—	—	—	—		TRG7CNT[2:0]	
MTU7	TADCR	BF[1:0]		—	—	—	—	—	—
		UT7AE	DT7AE	UT7BE	DT7BE	ITA6AE	ITA7VE	ITB6AE	ITB7VE
MTU7	TADCORA								
MTU7	TADCORB								
MTU7	TADCOBRA								

Table 4.2 List of I/O Registers (Bit Order) (23 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
GPT	GTBDR	BD33	BD32	BD31	BD30	BD23	BD22	BD21	BD20
		BD13	BD12	BD11	BD10	BD03	BD02	BD01	BD00
GPT	GTSWP	—	—	—	—	—	—	—	—
		—	—	—	—	SWP3	SWP2	SWP1	SWP0
GPT	LCCR	LPSC[1:0]		TPSC[1:0]		LCNTAT		LCTO[2:0]	
		—	LCINTO	LCINTD	LCINTC	—	LCNTS	LCNTCR	LCNTE
GPT	LCST	—	—	—	—	—	—	—	—
		—	—	—	—	—	LISO	LISD	LISC
GPT	LCNTA								
GPT	LCNT00								
GPT	LCNT01								
GPT	LCNT02								
GPT	LCNT03								
GPT	LCNT04								
GPT	LCNT05								
GPT	LCNT06								
GPT	LCNT07								
GPT	LCNT08								
GPT	LCNT09								
GPT	LCNT10								
GPT	LCNT11								
GPT	LCNT12								
GPT	LCNT13								
GPT	LCNT14								
GPT	LCNT15								
GPT	LCNTDU								
GPT	LCNTDL								
GPT0	GTIOR	OBHLD	OBDFLT			GTIOB[5:0]			
		OAHLD	OADFLT			GTIOA[5:0]			
GPT0	GTINTAD	ADTRBDEN	ADTRBUEN	ADTRADEN	ADTRAUEN	EINT	—	—	—
		GTINTPR[1:0]		GTINTF	GTINTE	GTINTD	GTINTC	GTINTB	GTINTA

Table 4.2 List of I/O Registers (Bit Order) (28 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
GPT3	GTCCRB								
GPT3	GTCCRC								
GPT3	GTCCRD								
GPT3	GTCCRE								
GPT3	GTCCRF								
GPT3	GTPR								
GPT3	GTPBR								
GPT3	GTPDBR								
GPT3	GTADTRA								
GPT3	GTADTBRA								
GPT3	GTADTDBRA								
GPT3	GTADTRB								
GPT3	GTADTBRB								
GPT3	GTADTDBRB								
GPT3	GTONCR	OBE	OAE	—	SWN	—	—	—	NFV
				NFS[3:0]		NVB	NVA	NEB	NEA
GPT3	GTDTCR	—	—	—	—	—	—	—	TDFER
		—	—	TDBDE	TDBUE	—	—	—	TDE
GPT3	GTDVU								
GPT3	GTDVD								
GPT3	GTDBU								
GPT3	GTDBD	—	—	—	—	—	—	—	—
		—	—	—	—	—	—	SOS[1:0]	
GPT3	GTSOS	—	—	—	—	—	—	—	—
		—	—	—	—	—	—	SOS[1:0]	
GPT3	GTSOTR	—	—	—	—	—	—	—	—
		—	—	—	—	—	—	—	SOTR
GPT0	GTDLYCR	—	—	—	—	—	—	—	—
		—	—	—	—	—	DLYEN	DLYRST	DLLEN
GPT1	GTDLYCR	—	—	—	—	—	—	—	—
		—	—	—	—	—	DLYEN	DLYRST	DLLEN

Table 5.4 Permissible Output Currents

Note: Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr. Ta is the same under conditions 1 to 3.

Item	Symbol	Min.	Typ.	Max.	Unit
Permissible output low current (average value per pin)	I_{OL}	-	-	2.0*1	mA
Permissible output low current (max. value per pin)	I_{OL}	-	-	4.0*1	mA
Permissible output low current (total)	ΣI_{OL}	-	-	110	mA
Permissible output high current (average value per pin)	$-I_{OH}$	-	-	2.0*1	mA
Permissible output high current (max. value per pin)	$-I_{OH}$	-	-	4.0*1	mA
Permissible output high current (total)	$\Sigma -I_{OH}$	-	-	35	mA

Caution: To protect the LSI's reliability, the output current values should not exceed the permissible output current.

Note 1. I_{OL} = 15 mA (max.)/ $-I_{OH}$ = 5 mA (max.) for P71 to P76 and P90 to P95. Note, however, that up to 6 (112-pin or 100-pin LQFP) or 3 (80-pin or 64-pin LQFP) pins can accept over 2.0-mA I_{OL} / $-I_{OH}$ at the same time.

Table 5.5 Permissible Power Consumption (Only for G Version)

Note: Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Ta = Topr. Ta is the same under conditions 1 to 3.

Item	Symbol	Typ.	Max.	Unit	Test Conditions
Total permissible power consumption*1	Pd	—	325	mW	85°C < Ta ≤ 105°C

Note: • Please contact Renesas Electronics sales office for derating of operation under Ta = +85°C to +105°C. Derating is the systematic reduction of load for improved reliability.

Note 1. The total power consmuption of the whole chip including output current.

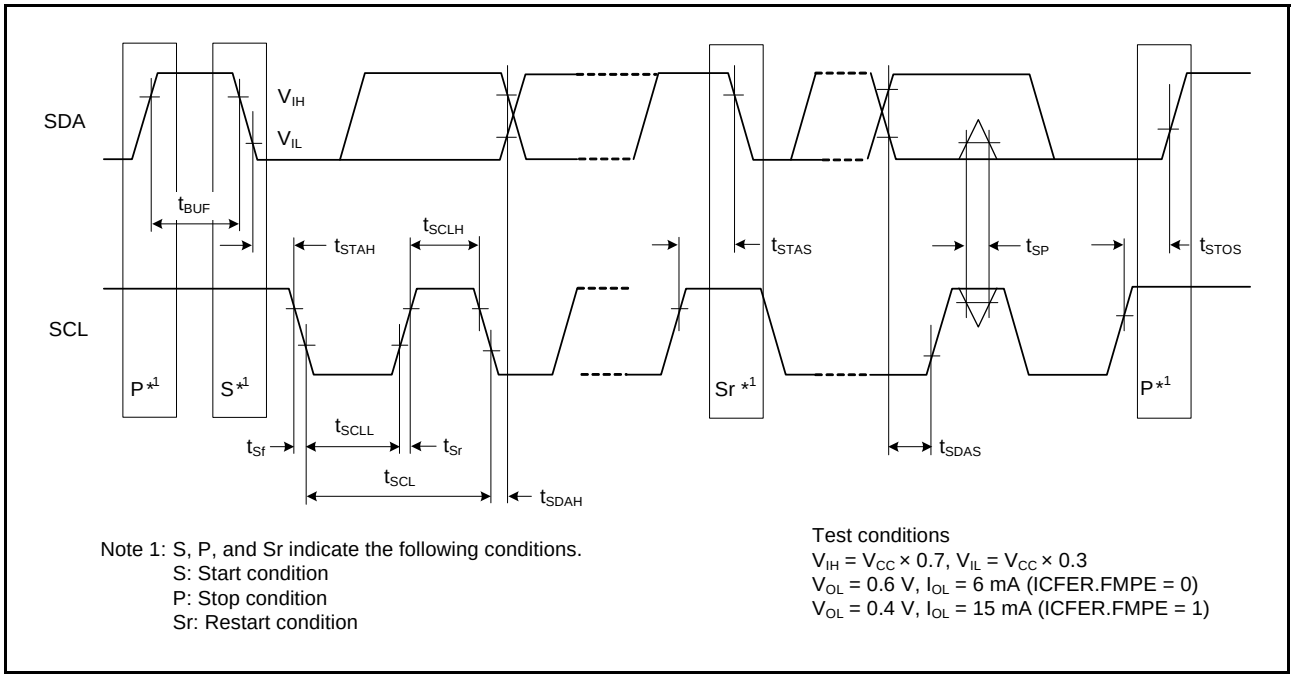


Figure 5.10 I2C Bus Interface Input/Output Timing

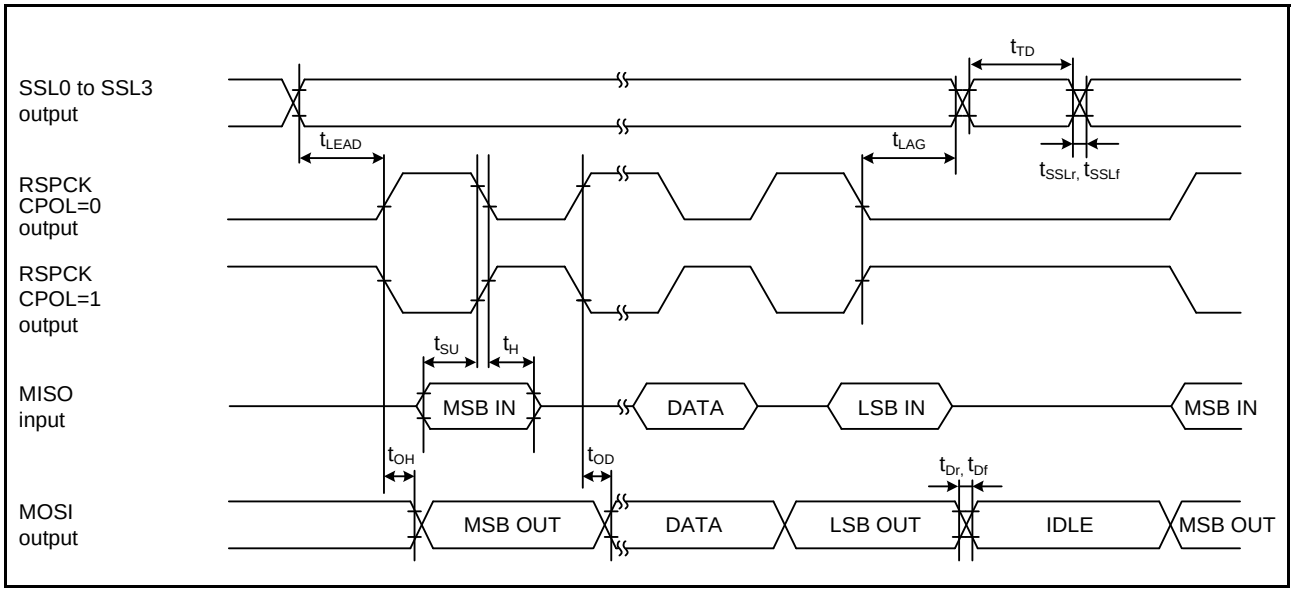


Figure 5.13 RSPI Timing (Master, CPHA = 1)

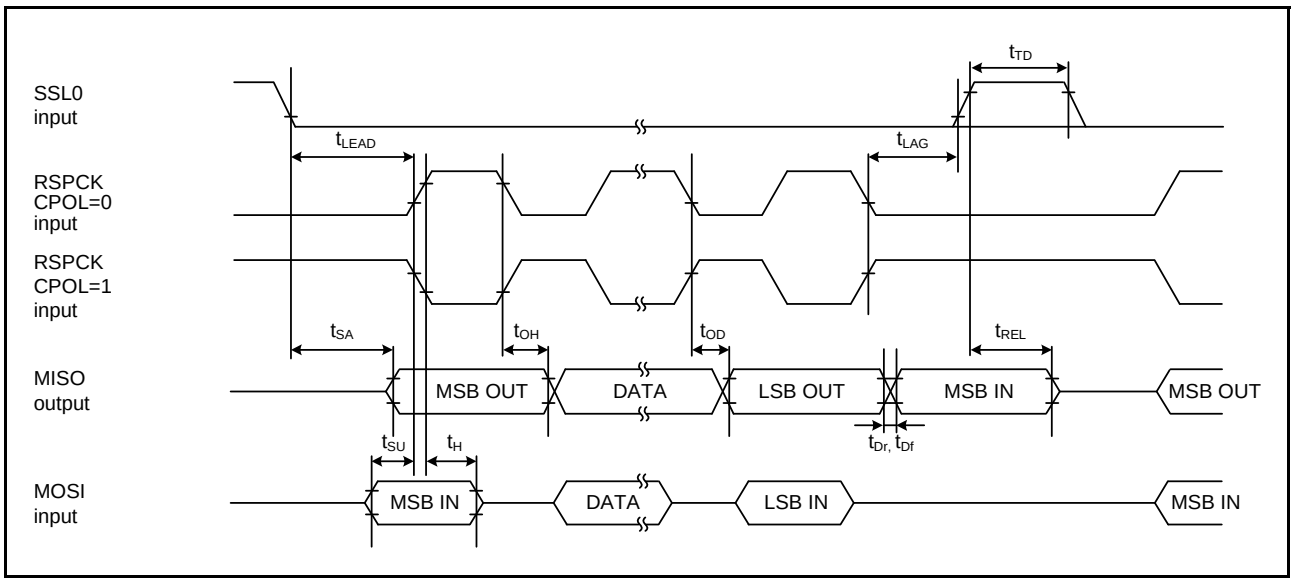


Figure 5.14 RSPI Timing (Slave, CPHA = 0)

Table 5.16 12-Bit A/D Conversion Characteristics

Note:Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC
Ta = Topr, ICLK = 8 to 100 MHz, PCLK = 8 to 50 MHz

Item		Min.	Typ.	Max.	Unit	Test Conditions
Resolution		12	12	12	Bit	
Conversion time*1 (AD clock = 25-MHz operation)		2.0	-	-	µs	Sampling 20 states
Analog input capacitance		-	-	6	pF	
Integral nonlinearity error		-	-	±4.0	LSB	
Offset error		-	-	±7.5	LSB	
Full-scale error		-	-	±7.5	LSB	
Quantization error		-	±0.5	-	LSB	
Absolute accuracy	When a sample-and-hold circuit is in use	-	-	±8.0	LSB	AVin = 0.25 to AV_{REFH} - 0.25
	When a sample-and-hold circuit is not in use	-	-	±8.0	LSB	AVin = AV_{REFL} to AV_{REFH}
Permissible signal source impedance		-	-	3.0	kΩ	

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr. Ta is the same under conditions 2 and 3. ICLK = 8 to 100 MHz, PCLK = 8 to 50 MHz.

Item		Min.	Typ.	Max.	Unit	Test Conditions
Resolution		12	12	12	Bit	
Conversion time*1 (AD clock = 25-MHz operation)		1.0	-	-	µs	Sampling 20 states
Analog input capacitance		-	-	6	pF	
Integral nonlinearity error		-	-	±4.0	LSB	
Offset error		-	-	±7.5	LSB	
Full-scale error		-	-	±7.5	LSB	
Quantization error		-	±0.5	-	LSB	
Absolute accuracy	When a sample-and-hold circuit is in use	-	-	±8.0	LSB	AVin = 0.25 to AV_{REFH} - 0.25
	When a sample-and-hold circuit is not in use	-	-	±8.0	LSB	AVin = AV_{REFL} to AV_{REFH}
Permissible signal source impedance		-	-	3.0	kΩ	

Note 1. The conversion time includes the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

5.5 Power-on Reset Circuit, Voltage Detection Circuit Characteristics

Table 5.19 Power-on Reset Circuit, Voltage Detection Circuit Characteristics

Note:Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr. Ta is the same under conditions 1 and 2.

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Power-on reset (POR)	V_{POR}	2.48	2.60	2.72	V	Figure 5.20
	Voltage detection circuit (LVD)	Vdet1	2.68	2.80	2.92		Figure 5.21
		Vdet2	2.98	3.10	3.22		Figure 5.22
Internal reset time		t_{POR}	20	35	50	ms	Figure 5.21 and Figure 5.22
Min. VCC down time*1		t_{VOFF}	200	-	-	us	Figure 5.20 to Figure 5.22
Reply delay time		tdet	-	-	200	us	

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	Power-on reset (POR)	V_{POR}	3.70	3.90	4.10	V	Figure 5.20
	Voltage detection circuit (LVD)	Vdet1	3.95	4.15	4.35		Figure 5.21
		Vdet2	4.40	4.60	4.80		Figure 5.22
Internal reset time		t_{POR}	20	35	50	ms	Figure 5.21 and Figure 5.22
Min. VCC down time*1		t_{VOFF}	200	-	-	us	Figure 5.20 to Figure 5.22
Reply delay time		tdet	-	-	200	us	

Note 1. The power-off time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det1}, and V_{det2} for the POR/ LVD.

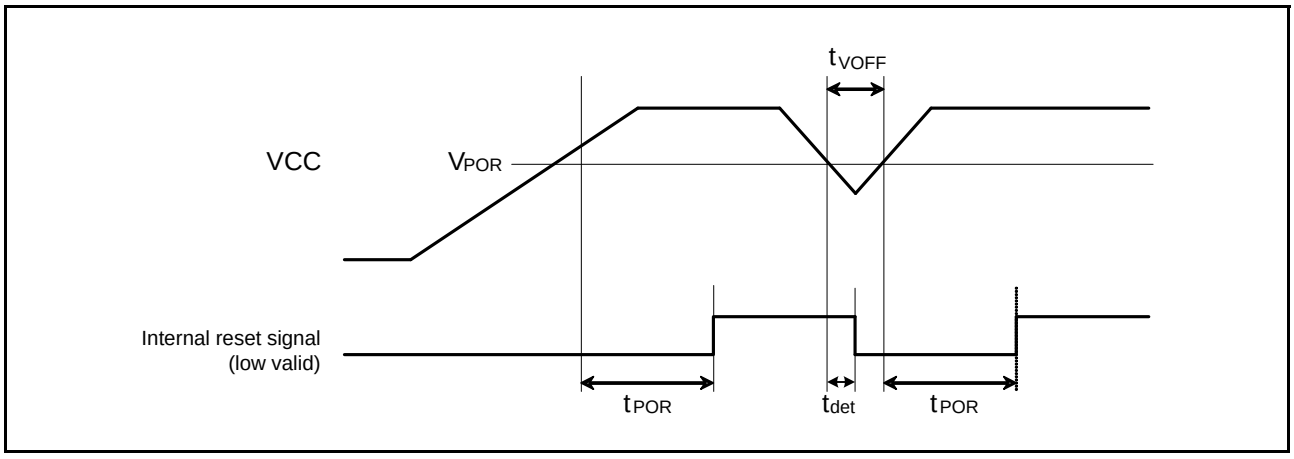
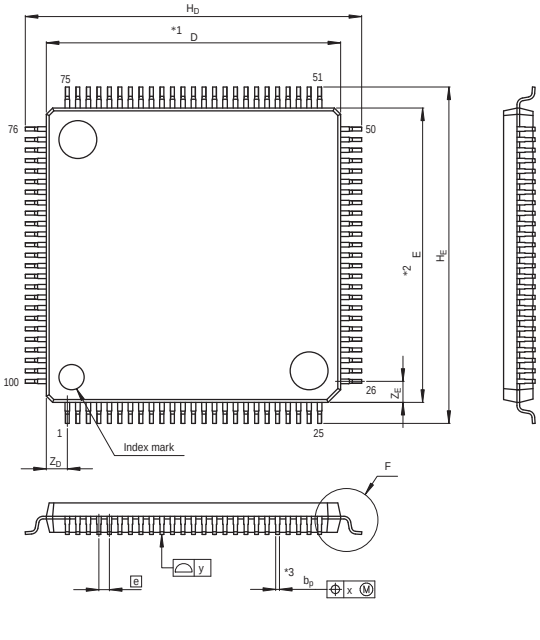
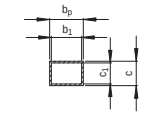
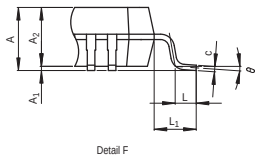


Figure 5.20 Power-on Reset Timing

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g







NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure B 100-Pin LQFP (PLQP0100KB-A) Package Dimensions

REVISION HISTORY — RX62T Group, RX62G Group Datasheet

Rev.	Date	Description	
		Page	Summary
1.00	Apr 20, 2011	—	First edition issued
1.30	May 22, 2013	1	Features, Package lineup, added
			1. Overview
		2	Table 1.1 Outline of Specifications (1/5) Description of CPU, added
		3	Table 1.1 Outline of Specifications (2/5) Description of Programmable I/O ports, changed
		6	Table 1.1 Outline of Specifications (5/5), 64-pin packaged, added
		7	Table 1.2 Functions of RX62T Group Products, 64-pin package, and MTU3/GPT complementary PWM pins added
		8	Table 1.3 List of Products, 64-pin package part number, changed
		9	Figure 1.1 How to Read the Product Part No., 64-pin package part number, changed
		9	Figure 1.1 How to Read the Product Part No., 5-V version, two-motor control supported, added
		10	Figure 1.2 Block Diagram, changed
		14	Figure 1.6 Pin Assignment of the 80-Pin LQFP (Two-motor Control Supported), added
		15	Figure 1.7 Pin Assignment of the 64-Pin LQFP, Figure PLQP0064GA-A, added
		25 to 27	Table 1.7 List of Pins and Pin Functions (80-Pin LQFP: R5F562TxGDFF) , added
		30 to 33	Table 1.9 Pin Functions, changed
			4. I/O Register
		38to 61	Table 4.1 List of I/O Registers (Address Order), MPU, added
		47	Table 4.1 List of I/O Registers (Address Order) TMOCNTL, TMOCNTU register, added
		57	Table 4.1 List of I/O Registers (Address Order), GTSWP register, added
			5. Electrical Characteristics
		62	Table 5.1 Absolute Maximum Ratings, note changed
		64	Table 5.2 DC Characteristics (1) (2/3) Test Conditions of P90 to P95, changed
		66	Table 5.3 DC Characteristics (2), note changed
		67	Table 5.4 Permissible Output Currents, note changed
		72	Table 5.7 Control Signal Timing, notes changed
		73	Table 5.8 Timing of On-Chip Peripheral Modules (1), changed
			Appendix 1.Package Dimensions
		96	Figure E 64-Pin LQFP (PLQP0064GA-A), added
2.00	Jan 10, 2014	1	Features, changed
			1. Overview
		2 to 6	Table 1.1 Outline of Specifications, changed; Note 1, added
		7, 8	Table 1.2 Functions of RX62T Group and RX62G Group Products, changed
		9, 10	Table 1.3 List of Products, changed; Note 1, added
		11	Figure 1.1 How to Read the Product Part No., changed
		15	Figure 1.6 Pin Assignment of the 80-Pin LQFP (Two-Motor Control Supported Version), added
		27 to 29	Table 1.7 List of Pins and Pin Functions (80-Pin LQFP: R5F562TxGDFF), added
			4. I/O Registers
		43 to 67	Table 4.1 List of I/O Registers (Address Order), changed
		68 to 97	Table 4.2 List of I/O Registers (Bit Order), changed
			5. Electrical Characteristics
		—	Conditions in the table, change to Ta = -40 to +105°C from Ta = -40 to +85°C.

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   — The characteristics of an MPU or MCU in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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